

1. CHARACTERISTICS

Transition Point (°C)	280
Deformation Point (°C)	310
Softening Point (°C)	348
Thermal Expansion Coefficient 40-250°C ($\times 10^{-6}/^{\circ}\text{C}$)	6.59
Specific Gravity (g/cc)	7.2
Dielectric Constant 1 MHz, 25°C	35.2
Volume Resistivity	
$\log_{10} (\Omega \text{ -cm})$ at 250°C	9.0
at 300°C	7.5
Dielectric Loss Tangent 1 MHz, 25°C	0.010
Acid Durability (mg/cm ²)	
1N HCL 25°C 5 min.	0.4
18N H ₂ SO ₄ 50°C, 5 min.	0.2
Thermal Conductivity 25°C (Cal/cm. sec. °C)	0.0037
Alpha/Emission ($\alpha/\text{cm}^2/\text{hr.}$)	4.5

2. RECOMMENDED PRE-CLEANING

Steps	Solution	Temp.	Period
a. De-scaling	50% H ₂ SO ₄	75°C - 95°C	1 min.
b. Tap water rinse		25°C	2 min. min.
c. Acid washing	10% H ₂ SO ₄	25°C	10 sec.
d. Tap water rinse		25°C	2 min. min.
e. Distilled water rinse		25°C	2 min. min.
f. Tin plating			

3. RECOMMENDED TIN PLATING CONDITION
3.1 Plating Solution

— Sulphuric Acid Bath

105 cc/liter

30 gram/liter

40 cc/liter

H₂SO₄

SnSO₄

Tinglo Culmo Starter Conc.

— Temperature of Plating Bath 17-21°C

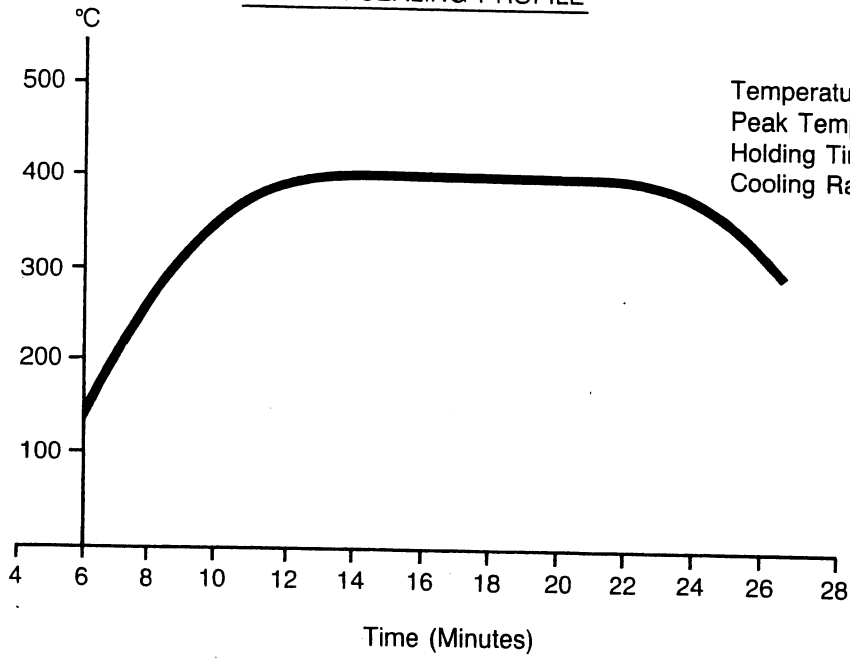
3.2 Current Density — 1.4-2.5 Ampere/SQ DM (Square Decimeter)

3.3 Plating Time 10 Minutes Max.



KC-400 DATA SHEET

TYPICAL SEALING PROFILE



Temperature Rise 40-90°C/Min
Peak Temperature 415-435°C
Holding Time at Peak 6-11 minutes
Cooling Rate 20-40°C/min.